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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **TSUNOI, et al.**

Serial No.: **09/805,559**

Filed: **March 14, 2001**

Group Art Unit: **2815**

Examiner: **H. NGUYEN**

P.T.O. Confirmation No.: 2664

FOR: MOUNTING METHOD OF SEMICONDUCTOR DEVICE

RESPONSE UNDER 37 CFR §1.116
- EXPEDITED RESPONSE -
GROUP ART UNIT 2815

BOX AF

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated **May 7, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please AMEND claim 6 to read as follows:

6. (Twice Amended) A structure comprising:
- a semiconductor device having bumps;
 - a board having pads so that each of the bumps is joined to a corresponding one of the pads, each of the pads per se having a concave surface with which a corresponding one of the bumps contacts; and
 - an insulating adhesive provided between the semiconductor device and the board,
- wherein

AF
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AUG -5 2002
TECHNOLOGY CENTER 2800
#9/D
Amend
H/E
J. Mcmillen
8/6/02
entered
August 1, 2002
J. Mcmillen
9/11/02

Sub
E-1
D-1